

## **Maximum Ratings** (@ $T_A = +25$ °C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characteristic	Symbol	DFLR1200	DFLR1400	DFLR1600	Units
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	200	400	600	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	140	280	420	V
Average Rectified Output Current (See Figure 4)	I <sub>O</sub>	1.0			А
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	25		А	

#### Thermal Characteristics

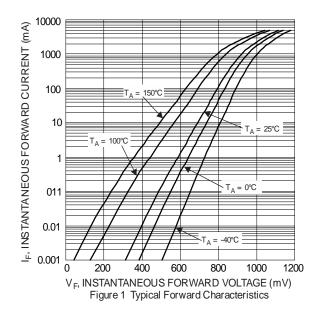
Characteristic	Symbol	Тур	Max	Unit
Thermal Resistance, Junction to Ambient Air (Note 5)	RθJA	134	_	°C/W
Thermal Resistance, Junction to Soldering Point (Note 6)	Rejs	_	6	°C/W
Operating and Storage Temperature Range	TJ, Tsтg	_	-65 to +150	°C

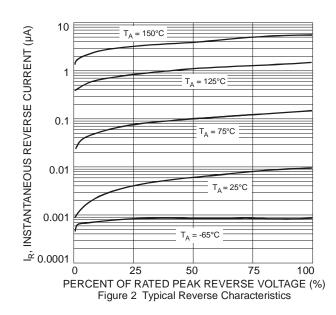
## Electrical Characteristic (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	DFLR1200	DFLR1400	DFLR1600	Unit
Minimum Reverse Breakdown Voltage (Note @I <sub>R</sub> =10µA	7)	$V_{(BR)R}$	200	400	600	V
Maximum Forward Voltage Drop @ I <sub>F</sub>	= 1.0A	V <sub>F</sub>	1.1		V	
	+25°C +125°C	I <sub>R</sub>	3.0 100		μΑ	
Typical Total Capacitance (f = 1MHz, $V_R$ = 4	.0VDC)	Ст		10		pF

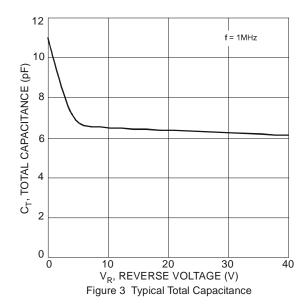
Notes:

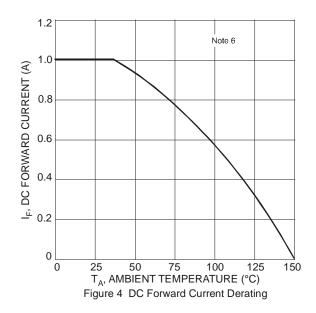
- 5. Theoretical ReJS calculated from the top center of the die straight down to the PCB/cathode tab solder junction.
- 6. Device mounted on 1in x 1in, FR-4 PCB; 2 oz Cu pad layout as shown on Diodes Incorporated's suggested pad layout document AP02001.pdf.
- 7. Short duration pulse test used to minimize self-heating effect.





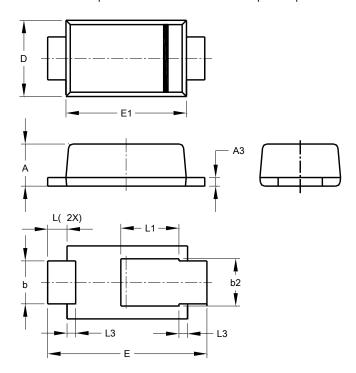






# **Package Outline Dimensions**

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



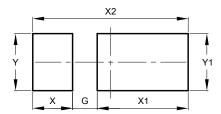
POWERDI <sup>®</sup> 123					
Dim	Min	Max	Тур		
Α	0.93	1.00	0.98		
A3	0.15	0.25	0.20		
b	0.85	1.25	1.00		
b2	1.025	1.125	1.10		
D	1.63	1.93	1.78		
E	3.50	3.90	3.70		
E1	2.60	3.00	2.80		
L	0.40	0.50	0.45		
L1	1.25	1.40	1.35		
L3	0.125	0.275	0.20		
All Dimensions in mm					



### **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

#### POWERDI®123



Dimensions	Value (in mm)		
G	0.65		
Х	1.05		
X1	2.40		
X2	4.10		
Υ	1.50		
Y1	1.50		

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